



PRODUCT CATALOG

ADHESIVES, SOLDERING MATERIALS & CLEANING SOLUTIONS



ADVANCED
TECHNOLOGY



HIGH
EFFICIENCY



CONSISTENT
QUALITY



SOLDER PASTE

High-Performance Solder Paste for SMT Assembly

Reliable solder paste for precision SMT printing and reflow soldering applications.

- Excellent printability
- Stable soldering performance
- Consistent wetting & solder joint quality
- Available in lead-free alloys
- Multiple flux options available

Alloy Composition: SAC305

Sn96.5Ag3.0Cu0.5

Flux Content: **10 - 12%**

Code	Flux Type	Powder Size	Packaging
JSZ-RH01-SAC305	No-Clean	Type 3 / Type 4 / Type 5	500g / 1kg
JSQ825HF-SAC305	No-Clean, Halogen-Free	Type 3 / Type 4 / Type 5	500g / 1kg
JSZ-RG01-SAC305	No-Clean	Type 3 / Type 4 / Type 5	500g / 1kg

Alloy Composition: SAC0307

Sn99.0Ag0.3Cu0.7

Flux Content: **10 - 12%**

Code	Flux Type	Powder Size	Packaging
JSZ-RG01-SAC0307	No-Clean	Type 3 / Type 4 / Type 5	500g / 1kg
JSQ825HF-SAC0307	No-Clean, Halogen-Free	Type 3 / Type 4 / Type 5	500g / 1kg

Alloy Composition: SAC105

Sn98.5Ag1Cu0.5

Flux Content: **10 - 12%**

Code	Flux Type	Powder Size	Packaging
JSZ-RH01-SAC105	No-Clean	Type 3 / Type 4 / Type 5	500g / 1kg
JSQ825HF-SAC105	No-Clean, Halogen-Free	Type 3 / Type 4 / Type 5	500g / 1kg



SOLDER WIRE

Lead-Free Solder Wire for Electronics Assembly

High-quality solder wire designed for reliable soldering performance in electronics assembly and PCB rework.

- Lead-free SAC & SnCu alloys
- No-Clean, RMA & Water-Soluble flux options
- Consistent soldering performance
- Multiple wire diameters
- Available in 500 g & 1 kg spools

Alloy Composition: SAC305

Sn96.5Ag3.0Cu0.5

Flux Content: **2.0 - 3.0%**

Code	Flux Type	Diameter	Spool
JS-SAC305	No-Clean	0.5 / 0.8 / 1.0 mm	500g / 1kg

Alloy Composition: SAC0307

Sn99.0Ag0.3Cu0.7

Flux Content: **2.0 - 3.0%**

Code	Flux Type	Diameter	Spool
JS-SAC0307	No-Clean	0.5 / 0.8 / 1.0 mm	500g / 1kg

Alloy Composition: SnCu0.7

Sn99.3Cu0.7

Flux Content: **2.0 - 3.0%**

Code	Flux Type	Diameter	Spool
JS-SC07	No-Clean	0.8 / 1.0 / 1.2 mm	500g / 1kg

SMT Assembly Applications



Stencil Printing



Component Placement



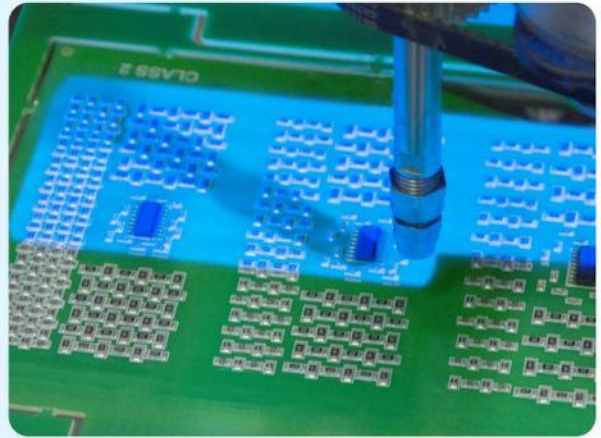
Reflow Soldering

2. Adhesive Solution

We offer a comprehensive range of adhesive solutions for electronics manufacturing, meeting diverse application needs - from component bonding and PCB protection to potting, encapsulation, and sealing.



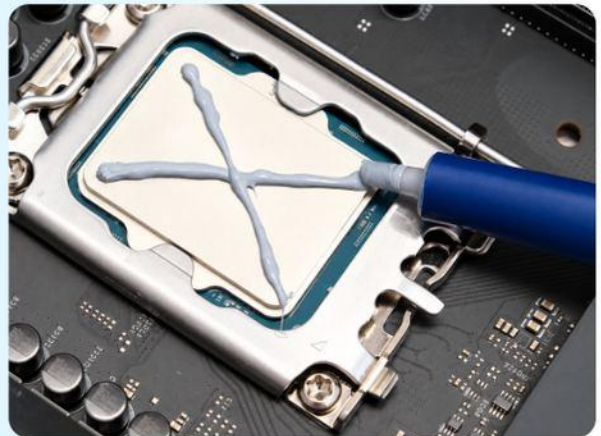
Silicone Adhesive



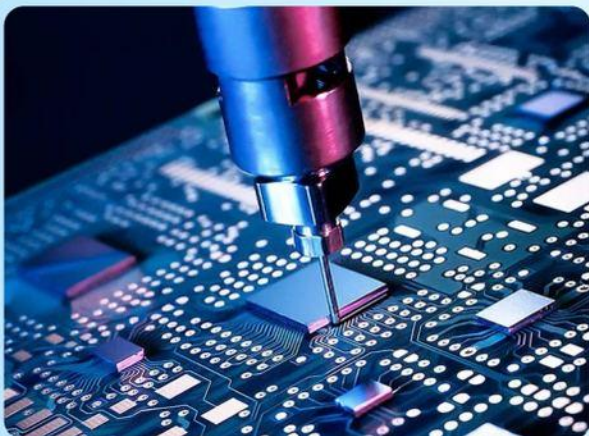
UV Adhesive



Epoxy Adhesive



Thermal Adhesive



Underfill Adhesive



Conformal Coating

IBOND ADHESIVES

HIGH-PERFORMANCE ADHESIVES
FOR ELECTRONIC MANUFACTURING



TUFFY GLUE (TF-323 SERIES)

LCD DISPLAY FIELD

- ✓ Peel & repair with zero residue
- 💧 Boil-resistant bond
- 🧪 ITO-safe formula

APPLICATIONS:

LCD sealing, OCA bonding, edge seal



GOB ENCAPSULANT (IBM-ER3010)

LCD DISPLAY FIELD

- 🔒 Full LED chip protection
- 💎 Crystal-clear and color-neutral
- 🌡️ Low shrinkage & heat-resistant

APPLICATIONS:

LED module, billboard, indoor screen



CONFORMAL COATING (CC-UV100 / CC-PU100)

PCB PROTECTION

- 🛡️ Moisture & fungus barrier
- 🌡️ Wide thermal range
- 🖌️ Flexible application

APPLICATIONS:

PCB assembly, automotive, industrial electronics



10:1 AB STRUCTURAL ADHESIVE (IB-7500 SERIES)

STRUCTURAL BONDING

- 🔗 Strong adhesion and good toughness
- 📄 Minimal surface treatment required
- 🛡️ High resistance to impact, fatigue, and various fuels

APPLICATIONS:

Laptop and TV structural assembly, precision electronic components, automotive assembly



IBOND NEW MATERIAL

OEM Solutions

IBOND – YOUR RELIABLE OEM PARTNER



Ideal Customer Profile

- ✓ Cost Reduction Initiatives
- ✓ New Project Development



What We Need From You

- ✓ Your Product
- ✓ Technical Data Sheet (TDS)
- ✓ Application Requirements



Our OEM Process



Why Choose iBOND?

**MADE FOR SUCCESS
BUILT FOR PARTNERSHIP**

35–50% Cost Savings

Rapid Technical Support

Fast Lead Time

Consistent Quality





FLUX-OFF® ROSIN

Plastic-Safe Flux Remover

A plastic-safe cleaner for removing rosin and no-clean flux from electronic assemblies.

- Safe for use on plastics
- Flammable
- Fast evaporation
- Leaves no residue
- All-Way Spray Aerosol



ES835B Spray

5 oz / 141 g BrushClean™ System

Component / Chemical Name	Concentration (%)
Ethanol	≥10 - ≤25
Isopropyl alcohol	≤10
N-hexane	≤3

CHEMASK® — PEELABLE

Fast-Curing Peelable Solder Mask

A fast-curing masking agent for protecting selected areas during soldering and assembly.

- Dries tack-free in 15 minutes
- Easy to use — simply peel off the dried masking agent
- Latex material compatible with all flux systems
- Stable when used with cleaning solvents



CM8 mask

8 fl oz / 236 ml squeeze bottle

Component / Chemical Name	Concentration (%)
Zinc bis(dibutylthiocarbamate)	≤5
Methanol	≤3
Titanium dioxide	≤3
Ammonia	≤1

WONDERMASK P

Low-Odor Peelable Solder Mask

Ammonia-free synthetic latex mask for temporary protection during soldering.

- Easy to peel
- Low odor
- Cure indicator — darkens as it cures
- Compatible with gold & copper leads
- Non-corrosive
- Nonflammable



2211-8SQ

8 fl oz / 237 ml squeeze bottle

Component / Chemical Name	Concentration (%)
Acrylic Latex Polymer	75 - 90%
Alkoxylated Alkylphenol	5 - 10%
Lecithin	1 - 5%
Other Minor Additives	≤5% each

FREEZE SPRAYS

Fast-Evaporating Cooling Spray

Rapidly cools localized areas to help troubleshoot faulty electronic components and reveal cold solder joints, cracks, and defective connections.

- Nonflammable
- Safe on plastics
- Zero residue
- Moisture-free
- Non-ozone depleting
- VOC exempt



1672-10S

10 oz / 283 g aerosol

Component / Chemical Name	Concentration (%)
Mixture	≥90
Cooling agents	≥10 - ≤25

FREEZE SPRAY

- Cools down to **-60°F (-51°C)**
- Nonflammable
- Safe for use on energized equipment

MAINTENANCE CLEANER

Powerful, Nonflammable Electronics Cleaner

Removes oil, grease and contaminants from electronic components and equipment.

- Nonflammable
- Safer alternative to industrial solvents
- Ideal for degreasing & contact cleaning
- Fast evaporation
- Aerosol or bulk formats available
- Suitable for vapor degreasing, ultrasonic & immersion cleaning
- Non-ozone depleting
- NSF registered K1 & K2



PWR-4 3400-G

1 gal. (3.8L) pail

Component / Chemical Name	Concentration (%)
Trans-Dichloroethylene	≥90%
Proprietary ingredients	Balance

ECO-DFLUXER SMT200

Eco-Friendly SMT Soldering Flux

High metal compatibility prevents oxidation and ensures clean solder joints.

- Prevents oxidation
- Eco-friendly formula
- Effective at low concentrations
- Suitable for no-clean, RMA, OA & halide-free fluxes
- Reduces shipping & disposal costs



1520-G

1 gal / 3.8 L plastic container

Component / Chemical Name	Concentration (%)
2-Amino-2-methylpropanol	10 - 25%
Proprietary ingredients	Balance

FLUX REMOVER

Effective Lead-Free Flux Cleaner

Effective flux remover for lead-free processes and sensitive plastics.

- Proven effective for lead-free processes
- Safe for sensitive plastics
- Suitable for cold & ultrasonic cleaning
- Available in aerosol and bulk formats
- K-2 classified



51621-10S

10 oz / 296 ml aerosol

Component / Chemical Name	Concentration (%)
Acetone	15 - 25
Ethylene glycol monobutyl ether	1 - 5
Limonene	1 - 5
Isopropyl alcohol	60 - 80

FLUX REMOVER

Effective Lead-Free Flux Cleaner

Efficiently removes flux from sensitive electronics and plastics.

- Effective for lead-free processes
- Safe for sensitive plastics
- Suitable for cold & ultrasonic cleaning
- K-2 classified



1620-10S

1 gal. (3.8L) pail

Component / Chemical Name	Concentration (%)
Ethanol	10 - 20
Isopropyl alcohol	7 - 15

NO-CLEAN FLUX DISPENSING PEN

No-Clean Flux Pen

Flux dispensing pen designed for easy application without post-soldering cleaning.

- Excellent wetting
- Compatible with lead & lead-free solder
- No cleaning required
- Improves wetting for lead-free solder



2507-N

11.5 ml individual pen

Component / Chemical Name	Concentration (%)
Isopropyl alcohol	≥50 - ≤75
Rosin	≥10 - ≤25
Adipic acid	≤5
Dimethyl glutarate	≤5

SODER-WICK® DESOLDERING BRAID

Fast & Clean Desoldering Braid

High-performance braid for fast, clean solder removal from PCBs and electronic components.

- Fast solder wicking action
- Clean & safe desoldering
- Minimizes heat damage during rework
- Available in Rosin, No-Clean &
- Lead-Free versions
- ESD-safe options available



Soder-Wick®

Sizes: #1 – #6

Available lengths
1.5 m / 3.0 m / 7.5 m / 15.0 m / 30.5 m / 152.5 m

CIRCUITWORKS® OVERCOAT PEN

Protective Acrylic Conformal Coating

Precision pen applicator for tough, durable protection of circuit traces.

- Easy-to-use, one-component formula
- Hard & durable coating
- High dielectric strength
- Fast room-temperature curing
- Protects against moisture & abrasion
- Meets MIL-I-46058C & IPC-CC-830A



CW3300G

Green

4.9 g / 0.16 oz

Component / Chemical Name	Concentration (%)
Propyl acetate	≥10 – ≤30
Butanone	≥10 – ≤30
Other components	Balance

CIRCUITWORKS® CONDUCTIVE PEN

Precision Conductive Silver Pen

Pen dispenser for creating highly conductive silver traces, jumpers, and shielding on circuit boards.

- Creates highly conductive silver traces
- Precision valve-tip application
- Low-temperature solderable
- Dries within minutes at room temperature
- Standard Tip & Micro Tip options



CW2200MTP

Micro Tip

8.5 g / 0.3 oz

Component / Chemical Name	Concentration (%)
Silver Content	55% ± 2%
Other components	Balance

JC-Q203 CLEANER

Water-Based Cleaner

For cleaning stencils, PCBA surfaces, solder paste, flux and post-soldering fixtures.

- Strong cleaning performance for solder paste and flux
- Excellent wetting and penetration
- Ultrasonic & immersion cleanin
- Suitable for lead-free processes
- Non-corrosive to fixtures and stencils
- No metal whitening after cleaning
- Halogen-free, ODS-free & RoHS compliant



JC-Q203

25kg / drum

Component / Chemical Name	Concentration (%)
Surfactant	3–5%
Sodium Metasilicate Pentahydrate	5–10%
Propylene Glycol Butyl Ether	2–5%
Deionized Water	Balance

Specifications

- Cleaning Temperature: 40–50°C
- Cleaning Time: 5–20 min
- Dilution: Up to 20×
- PH: 12–14
- Specific Gravity: 1.00–1.10 @ 25°C
- Appearance: Colorless, transparent liquid

JC-A02

Water-Based Nano-Powder Cleaner



**WATER-BASED
& NON-FLAMMABLE**



ODORLESS



**COMPACT POWDER
PACKAGING**



**RoHS & REACH
COMPLIANT**



CLEANING APPLICATIONS

ELECTRONICS



AUTOMOTIVE & NEW ENERGY



AEROSPACE & MARINE



MACHINERY MANUFACTURING



DILUTION RATIO

1 : 20 – 1 : 50

Adjust to
contamination level.



OPERATING TEMP

20 – 90°C

Improves cleaning
performance.

JC-A02

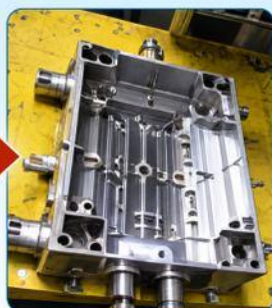
1 kg/bag

Component / Chemical Name	Concentration (%)
Elementary Sodium Dodecyl-benzene Sulfonate	10 - 30%
Sodium silicate	8 - 20%
Sodium carbonate	6 - 20%
Sodium sulfate;Anhydrous	Balance

CLEANING RESULTS



BEFORE



AFTER



BEFORE



AFTER



- **JIT Shenzhen Technology Co., Ltd**
- **JIT Technology (Hong Kong) Co.**
- **JIT Industrial Asia Pte Ltd**
- **JIT Industrial Viet Nam Co., Ltd**
- **JIT Industrial Americas LLC**
- **JIT Industrial (M) Sdn Bhd**
- **PT JIT Industrial Indonesia**
- **Electronics Industrial Philippines Inc.**
- **JIT Industrial (Thailand) Co., Ltd**

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